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**ABSTRACT OF THE INVENTION**

A method of passivating an integrated circuit (IC) is provided. An insulating layer is formed onto the IC. An adhesion layer is formed onto a surface of the insulating layer by treating the surface of the insulating layer with a gas. A first  
5 passivation layer is formed upon the adhesion layer, the first passivation layer and the gas including at least one common chemical element.

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